

Specifications

Insulation Resistance:	500MΩ at 150V DC
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
Contact Resistance:	30mΩ max. at 10mA and 20mV
Operating Temp. Range:	-25°C to +85°C
Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
 Contact: Beryllium Copper (BeCu)
 Plating: SnPb 2.0 ~ 4.0μm over 2.5 ~ 4.5μm Ni = S5
 Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5

Part Number (Details)

IC149 - 100 - *54 - *5 1

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

Contact Plating:

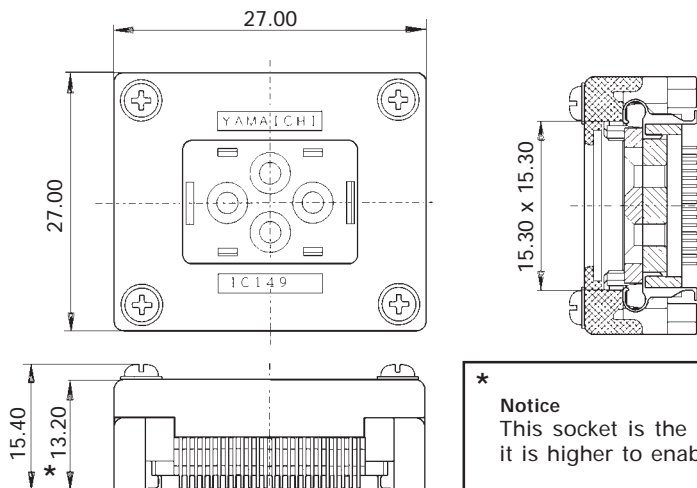
S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

0 = without Screws 1 = with Screws

Compatible Emulation-Adapter ICP-100-5

Outline Socket Dimensions (Reference Only)

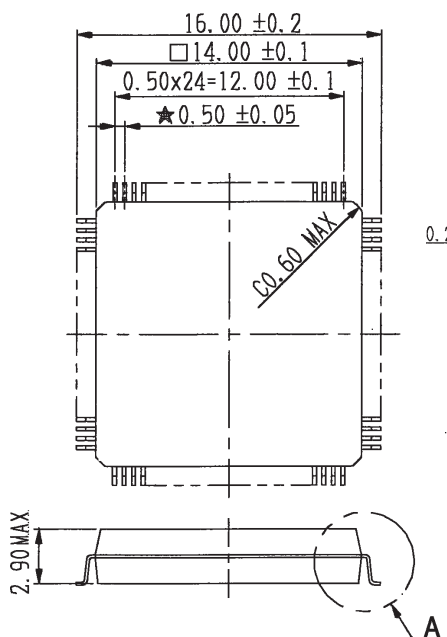


Remarks

1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

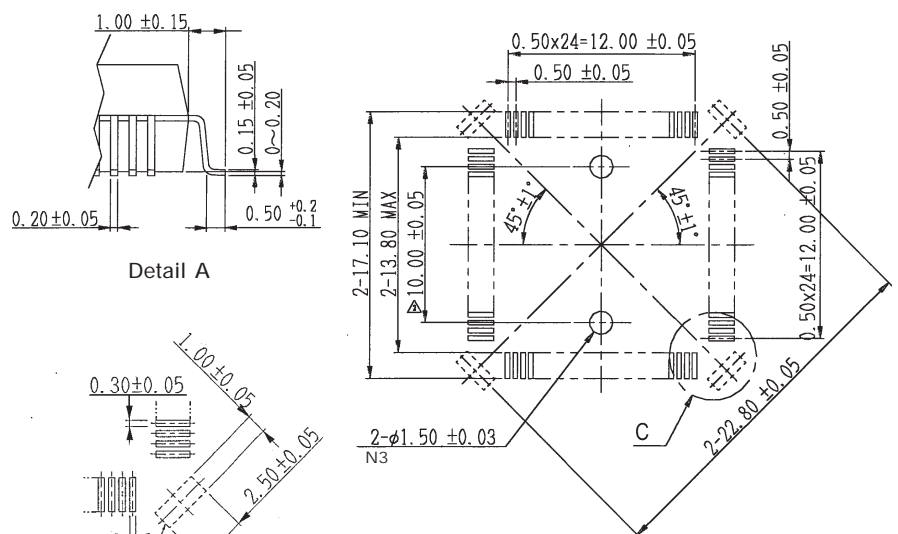
*** Notice**
 This socket is the same as IC149-100-*25-S5, except it is higher to enable an easier soldering by hand

IC - Dimensions



Socket PCB-Layout

Top View from Socket



Notes

- N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.
 N3: These holes are only necessary for use with positioning pins.

IC149 Series (SMT)

QFP/TQFP - 100 Pins (25x25) 0.5mm pitch

Specifications

Insulation Resistance:	500M Ω at 150V DC
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
Contact Resistance:	30m Ω max. at 10mA and 20mV
Operating Temp. Range:	-25°C to +85°C
Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
 Contact: Beryllium Copper (BeCu)
 Plating: SnPb 2.0 ~ 4.0 μ m over 2.5 ~ 4.5 μ m Ni = S5
 Au 0.3 μ m min. over 2.5 ~ 4.5 μ m Ni = B5

Part Number (Details)

IC149 - 100 - *25 - *5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

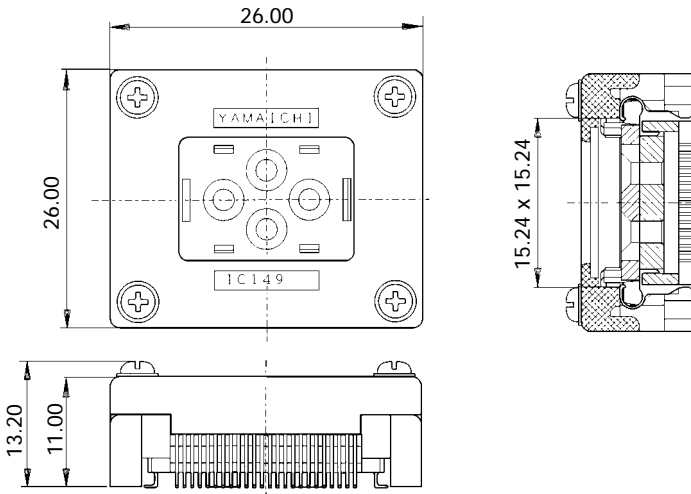
Contact Plating:

S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

Compatible Emulation-Adapter ICP-100-5

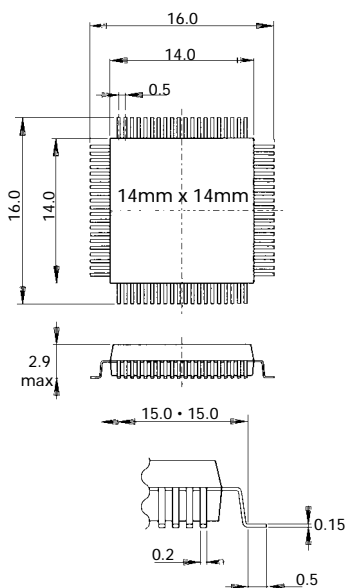
Outline Socket Dimensions (Reference Only)



Remarks

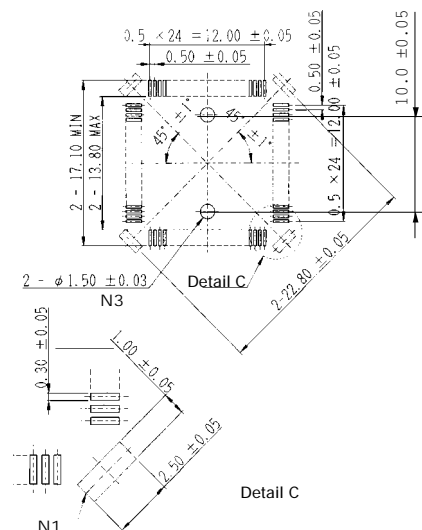
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3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

IC - Dimensions



Socket PCB-Layout

Top View from Socket



Notes

- N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.
 N3: These holes are only necessary for use with positioning pins.

IC149 Series (SMT)

BQFP - 100 Pins (25x25) 0.635mm pitch

Specifications

Insulation Resistance:	500MΩ at 150V DC	
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute	
Contact Resistance:	30mΩ max. at 10mA and 20mV	
Operating Temp. Range:	-25°C to +85°C	
Reflow-soldering Temp.:	220°C for 60 seconds	
Mating Cycles:	20 insertions maximum	
Solvent Durability:	Freon	
Allowable Torque (max.):	- for 1-time screw connection	= max 0.147 Nm
	- for repetitive screw connection	= min 0.078 Nm max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
 Contact: Beryllium Copper (BeCu)
 Plating: SnPb 2.0 ~ 4.0μm over 2.5 ~ 4.5μm Ni = S5
 Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5

Part Number (for IC-use)

IC149 - 100 - *28 - S5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

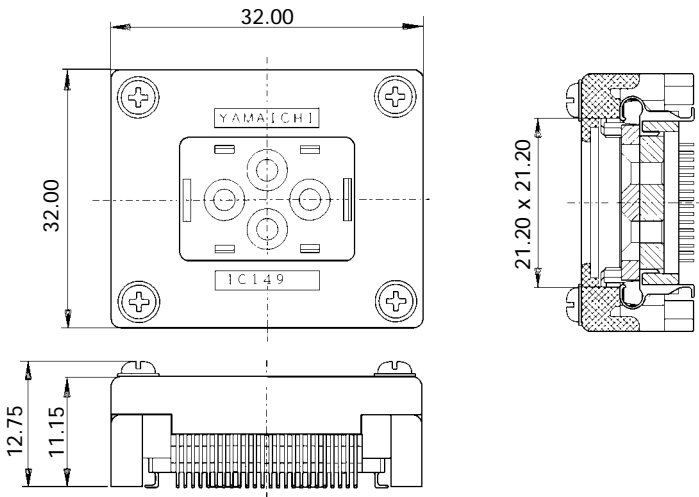
1 = With Pins

Contact Plating:

S5 = SnPb

Compatible Emulation-Adapter not available

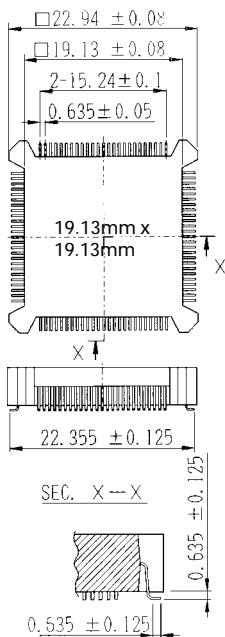
Outline Socket Dimensions (Reference Only)



Remarks

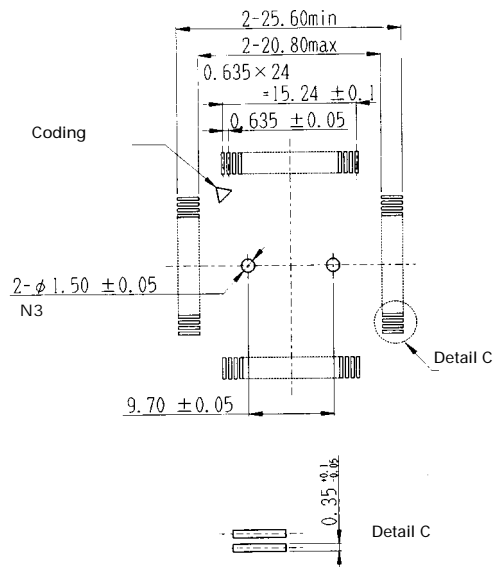
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3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

IC - Dimensions



Socket PCB-Layout

Top View from Socket



Notes

N3: These holes are only necessary for use with positioning pins.

Specifications

Insulation Resistance: 500M Ω at 150V DC
Withstanding Voltage: 100V_{eff} to 700V_{eff} for 1 minute
Contact Resistance: 30m Ω max. at 10mA and 20mV
Operating Temp. Range: -25°C to +85°C
Reflow-soldering Temp.: 220°C for 60 seconds
Mating Cycles: 20 insertions maximum
Solvent Durability: Freon
Allowable Torque (max.): - for 1-time screw connection = max 0.147 Nm
- for repetitive screw connection = min 0.078 Nm
max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
Contact: Beryllium Copper (BeCu)
Plating: SnPb 2.0 ~ 4.0 μ m over 2.5 ~ 4.5 μ m Ni = S5
Au 0.3 μ m min. over 2.5 ~ 4.5 μ m Ni = B5

Part Number (Details)

IC149 - 100 - *14 - *5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

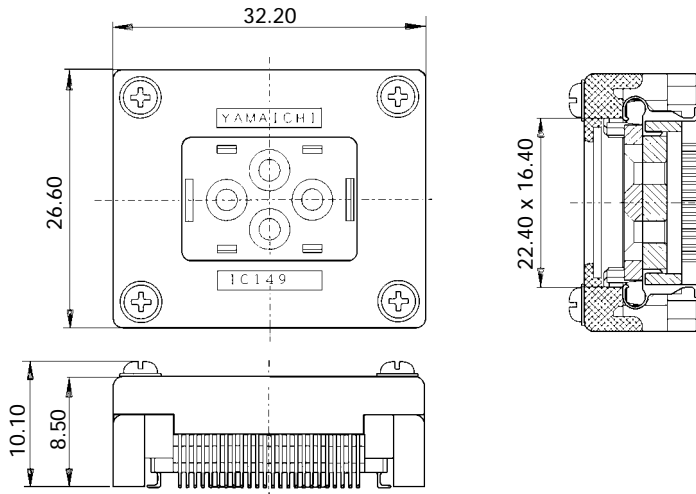
Contact Plating:

S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

Compatible Emulation-Adapter ICP-100-4-4 (with 4 x M2.0 -12.0mm)

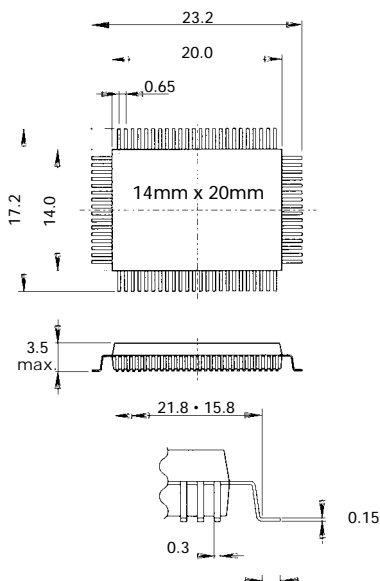
Outline Socket Dimensions (Reference Only)



Remarks

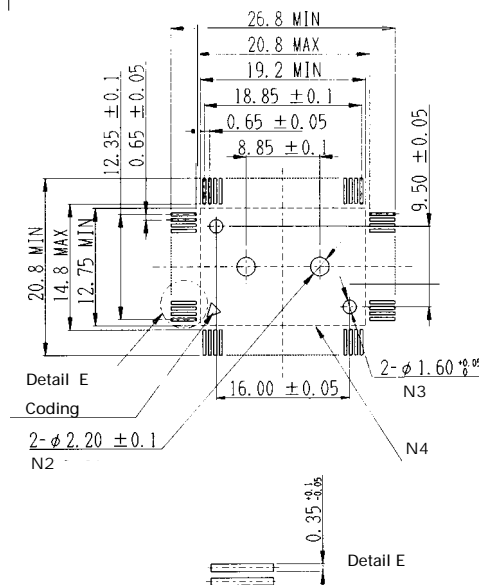
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2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

IC - Dimensions



Socket PCB-Layout

Top View from Socket



Notes

- N2: These holes are only necessary when fixing the Socket with screws.
N3: These holes are only necessary for use with positioning pins.
N4: The Socket may be glued to the PC Board within this area.

Specifications

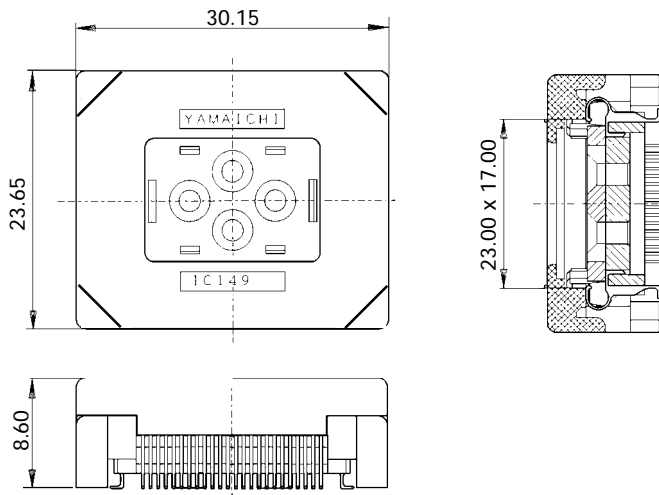
Insulation Resistance: 500MΩ at 150V DC
 Withstanding Voltage: 100V_{eff} to 700V_{eff} for 1 minute
 Contact Resistance: 30mΩ max. at 10mA and 20mV
 Operating Temp. Range: -25°C to +85°C
 Reflow-soldering Temp.: 220°C for 60 seconds
 Mating Cycles: 20 insertions maximum
 Solvent Durability: Freon

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
 Contact: Beryllium Copper (BeCu)
 Plating: SnPb 2.0 ~ 4.0μm over 2.5 ~ 4.5μm Ni = S5
 Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5

Extra Feature: Clipped Cover

Outline Socket Dimensions (Reference Only)



Part Number (for IC-use)

IC149 - 100 - *05 - S5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

Contact Plating:

S = SnPb

Part Numbers (for Adapter-use)

IC149-100-KS11113-0 (w/o pos. pins)

IC149-100-KS11113-1 (with pos. pins)

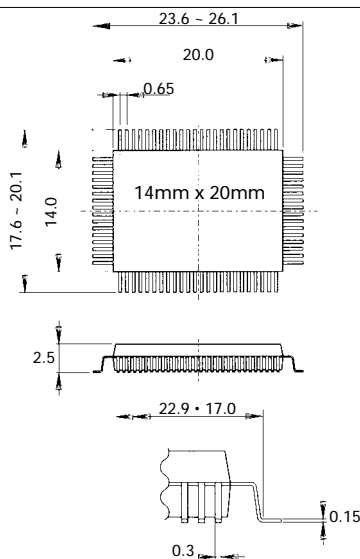
Compatible Emulation-Adapter

ICP-100-4-1 (with 2 x M2.5 -12.0mm)

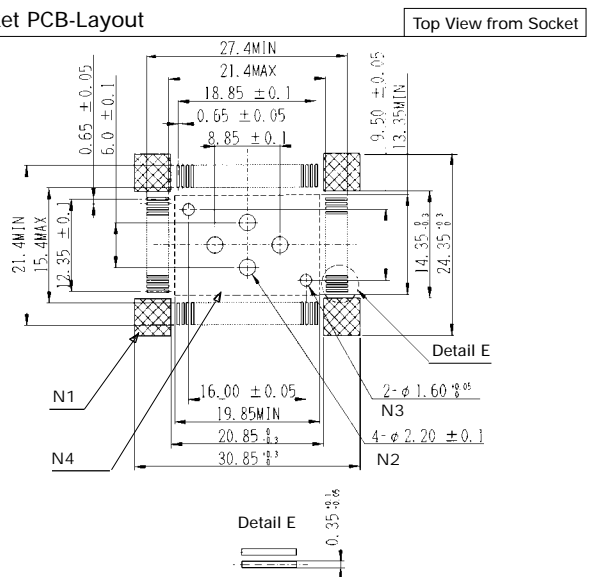
Remarks

1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

IC - Dimensions



Socket PCB-Layout



Notes

- N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.
- N2: These holes are only necessary when fixing the Socket with screws.
- N3: These holes are only necessary for use with positioning pins.
- N4: The Socket may be glued to the PC Board within this area.